



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: [info@chipsmall.com](mailto:info@chipsmall.com) Web: [www.chipsmall.com](http://www.chipsmall.com)

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## 10072353-X01-XXLF

S = 0.38 $\mu$ m GOLD/GXT DN CONTACT AREA  
2.0 $\mu$ m MIN MATTE TIN DN TAIL

ROHS COMPATIBLE  
NOTE 6

G = 0.76μm GOLD/GXT ON CONTACT AREA  
2.0μm MIN MATTE TIN ON TAIL

PACKAGING  
NOTE 5

F = GOLD FLASH ON CONTACT AREA  
2.0μm MIN MATTE TIN ON TAIL

NB OF POSITIONS PER ROW  
02 TO 25 PDS

1.27  $\mu\text{m}$  MIN NICKEL UNDERPLATING



1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC  
UL 94V-0, COLOR BLACK

2. MATERIAL TERMINAL: COPPER ALLOY

3. TO DETERMINE DIMENSIONS:  
N = NUMBER OF POSITIONS PER ROW.

4. 7N MIN PIN RETENTION IN EITHER DIRECTION.

## 5. PACKAGING :

PLASTIC BOX

U = TUBE AVAILABLE FROM 06 TO 50 POS  
6. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

α - PLATING

= "LF" MEANS THE PRODUCT IS LEAD-FREE  
2µm MINIMUM MATTE TIN OVER 127µm  
MINIMUM NICKEL UNDERPLATE.




## 6 - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 30 SECONDS MAX IN A CONVECTION, INRA-RED DR VAPOR PHASE OR REFLOW OVEN.

## C - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920.

d - THIS PRODUCT MEETS EUROPEAN DIRECTIVES  
AND OTHER COUNTRY REGULATIONS AS DISCRIBED  
IN GS-47-0004

www.fciconnect.com		surface - 		tolerance std ISO 1302    ISO 406    ISO 1101		projection 		mm 	
		TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	L MULIN	06.09.14	ANGULAR		0.X	± 0.13	size	A3	Scale
Eng	J COMPAGNON	06.09.14	LINEAR		0.XX	± 0.05			5:1
Chr	-	-	0° ± 2°		0.XXX	± -	ECN		-
Appr	JM.C	06.09.14	Product family		Mintek		Spec ref		-
title		UNSHR HEADER		no		1007/2353		Rev.	
RIGHT ANGLE PIP				dwg				C	
catalog no		-		CUSTOMER Drawing		sheet 1 of 1			
